

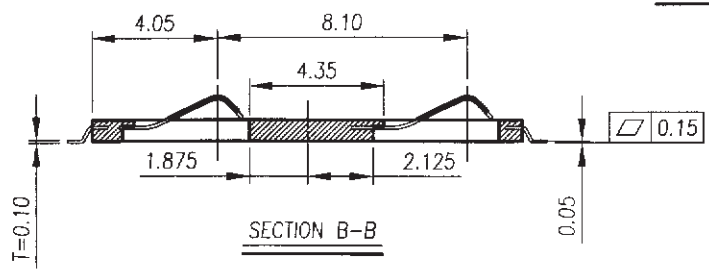
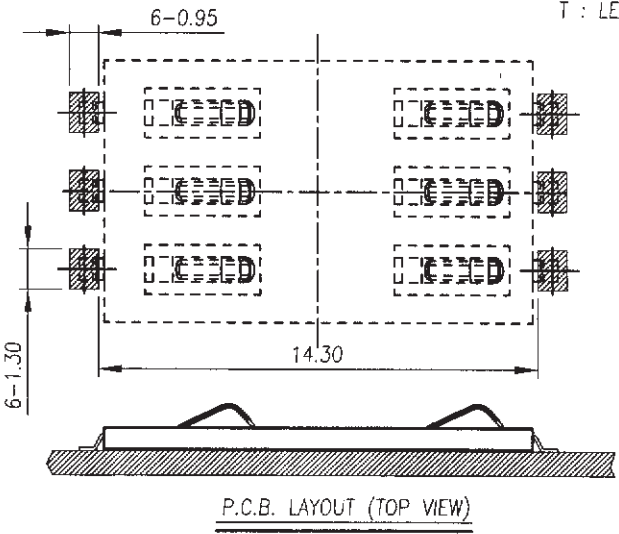
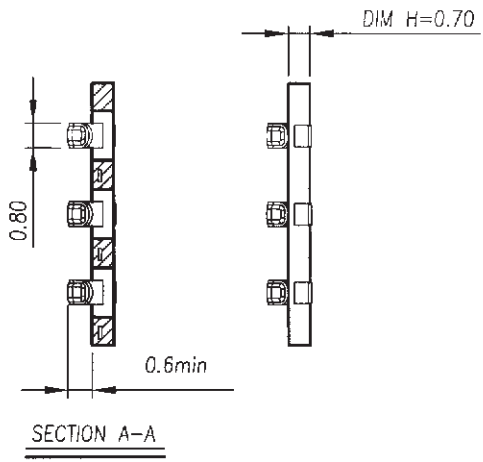
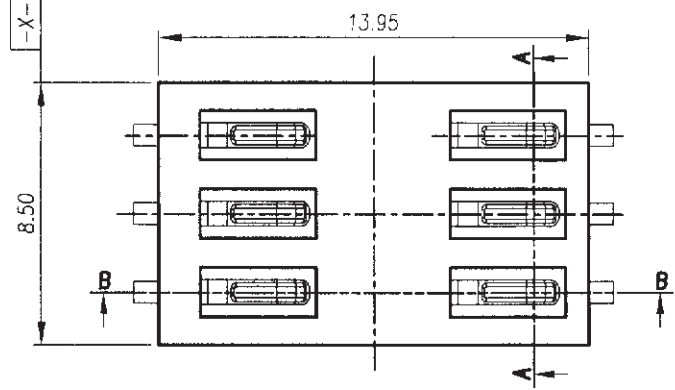
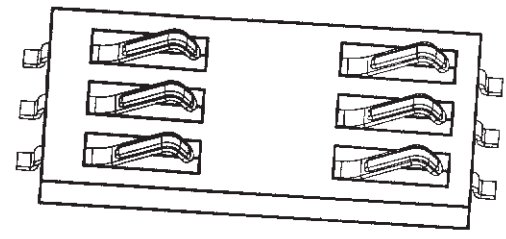
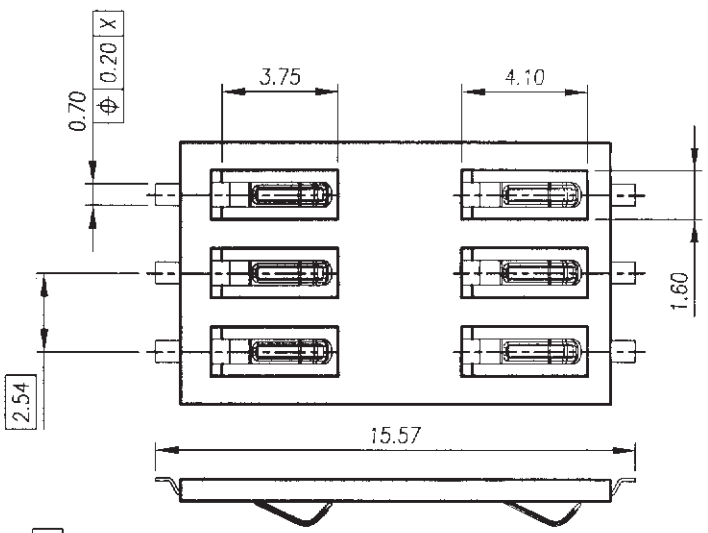
REV	MODIFICATION	DATE	DRAW
B	EN-04-0419	04.14.04"	Aaron
C	EN-04-0505	05.12.04"	Aaron
D	EN-05-0902	09.02.05"	Stacey

NOTES:

- Material :
Housing : Thermoplastic UL94V-0
Contact : BERYLLIUM C17200R-H,T=0.10mm
- Plating :
Contact Plating - Gold over 45u" MIN.Nickel
Solder Tail Plating - Gold over 45u" MIN.Nickel
- Contact Forces :
Max. 0.5 N For 0.65mm Contact Deflection.
Min. 0.25 N For 0.65mm Contact Deflection.
- Order Information :
SIMMP-006XXBXX2
PLATING 0 : TAPE REEL
30 : GOLD PLATING 30u". 1 : TUBE.
 0 : TIN/LEAD PLATING
T : LEAD FREE

F
E
D
C
B
A

F
E
D
C
B
A



DIMENSION IN mm [Inch]		PROD. SPEC. SP0052	ALMITA CO., LTD.	
TOLERANCE UNLESS OTHERWISE SPECIFIED		PKG. SPEC. PPP-SIM-002	Subscriber Identify Module Card Simple Style Conn. .6 Pin Same Direction Type 0.70mm	
.X±0.30	.X'± 1'	APPROVE <i>AK/15</i>	FILE NO. KFP-052	DWG NO. SIMMP-006XXBXX2
.XX±0.20	.X'± 0.5'	CHECK <i>劉忠朋</i>	SIZE A4	PROJ. SHEET 1 / 1
.XXX±0.10	.XX'± 0.25'	DRAW <i>Steen</i>	SCALE 4:1	REV D